SEMICONDUCTOR WAFER TRANSPORT METHOD AND SEMICONDUCTOR WAFER TRANSPORT APPARATUS

ABSTRACT OF THE DISCLOSURE

A semiconductor wafer joined to a carrier via a double-faced adhesive tape having an adhesive layer of a heating separation property is heated for removal from the carrier. The double-faced adhesive tape is separated from the semiconductor wafer on a holding table. Thereafter, an air nozzle preliminarily cools the semiconductor wafer for a given time during transportation with a wafer transport section. Upon completion of the preliminary cooling, the semiconductor wafer is placed on a cooling stage to cool it to a target temperature.

Figure 5